

DSK9J01

Silicon N-channel Junction FET

For low frequency amplification

For pyroelectric sensor

DSK5J01 in SSMini3 type package

■ Features

- High gate-drain voltage (source open) V_{GDO}
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Gate-drain breakdown voltage	V_{GDS}	-55	V
Drain current	I_D	30	mA
Gate current	I_G	10	mA
Power dissipation	P_D	125	mW
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Package

- Code
SSMini3-F3-B
- Pin Name
1: Source
2: Drain
3: Gate

■ Marking Symbol: B6

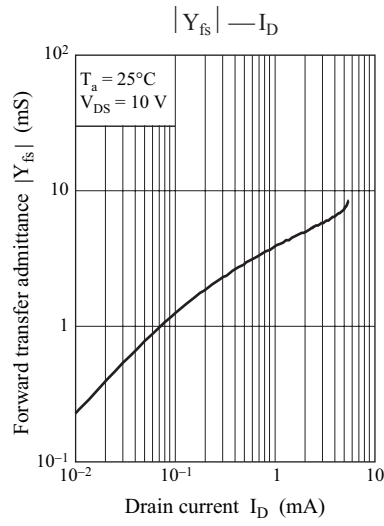
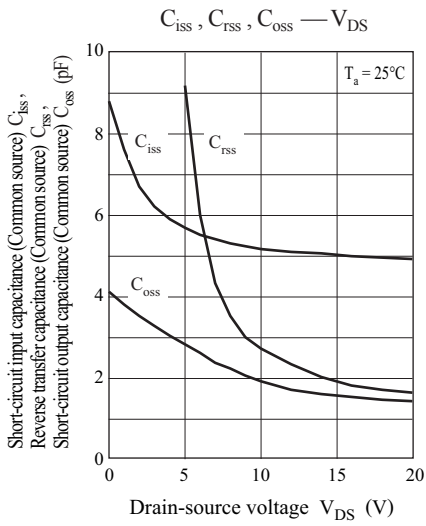
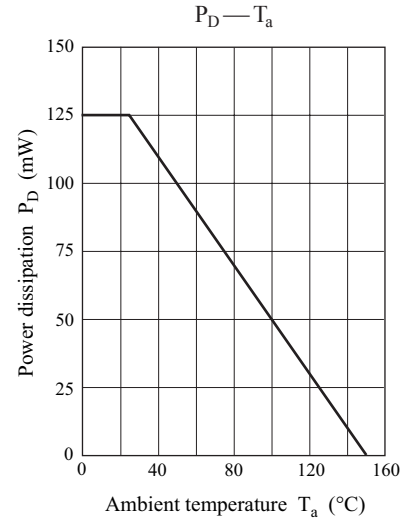
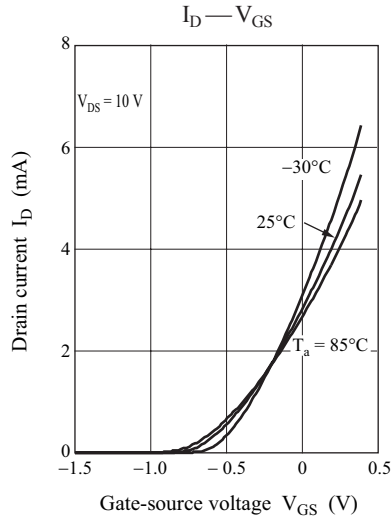
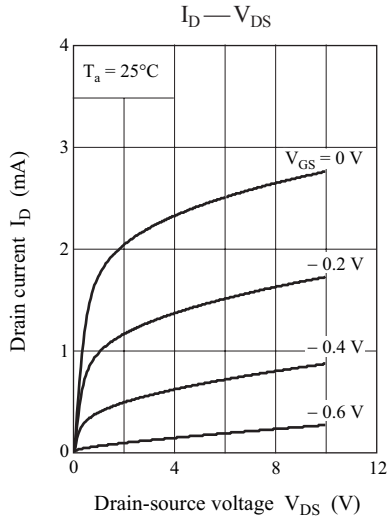
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Gate-drain breakdown voltage	V_{GDS}	$I_G = -100 \mu\text{A}, V_{DS} = 0$	-55			V
Drain-source cutoff current *	I_{DSS}	$V_{DS} = 10 \text{ V}, V_{GS} = 0$	1.0		6.5	mA
Gate-source cutoff current	I_{GSS}	$V_{GS} = -30 \text{ V}, V_{DS} = 0$			-10	nA
Gate-source cutoff voltage	V_{GSC}	$V_{DS} = 10 \text{ V}, I_D = 10 \mu\text{A}$			-5	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ mA}, f = 1 \text{ MHz}$	2.5	7.5		mS
Short-circuit input capacitance (Common source)	C_{iss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		6.0		pF
Reverse transfer capacitance (Common source)	C_{rss}			2.5		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

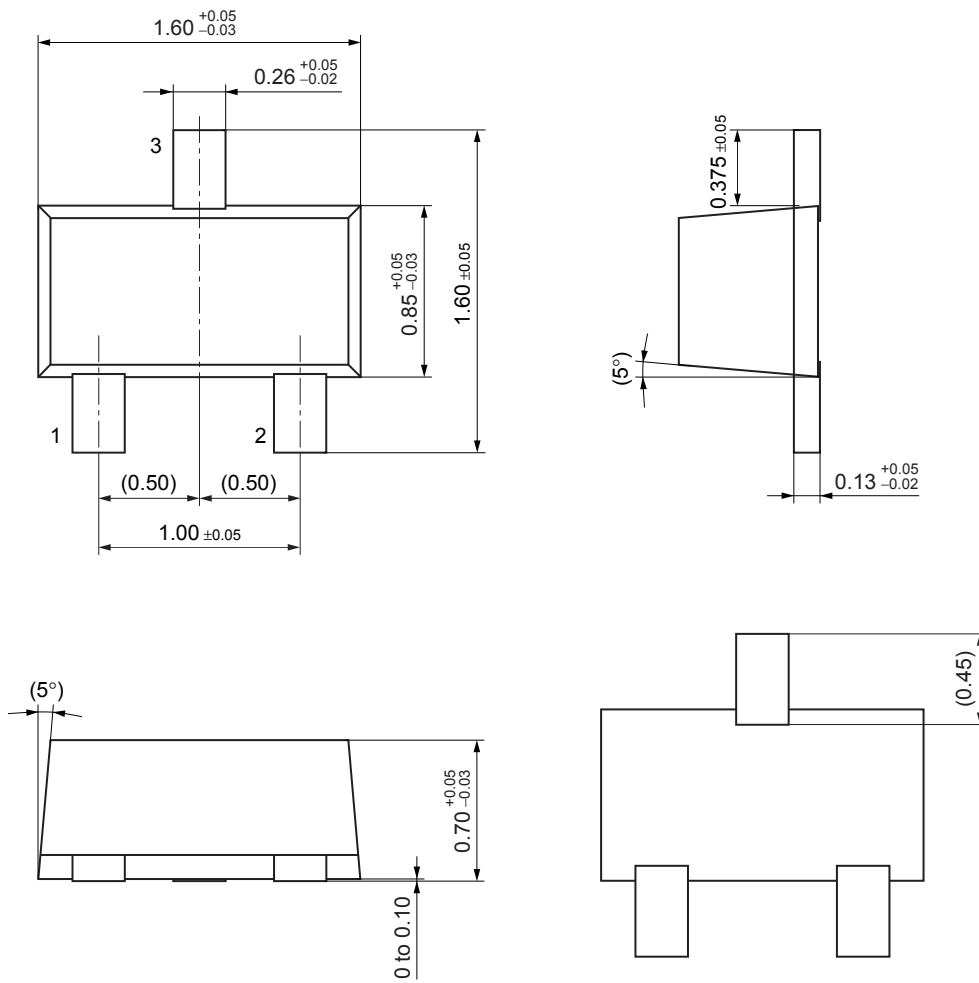
2. *: Rank classification

Code	P	Q
Rank	P	Q
I_{DSS}	1.0 to 3.0	2.0 to 6.5
Marking Symbol	B6P	B6Q



SSMini3-F3-B

Unit: mm



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